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N-Channel PowerTrench[®] MOSFET 30 V, 200 A, 0.65 m Ω

Features

- Max $r_{DS(on)}$ = 0.65 m Ω at V_{GS} = 10 V, I_D = 55 A
- Max $r_{DS(on)}$ = 0.9 m Ω at V_{GS} = 4.5 V, I_D = 47 A
- \blacksquare Advanced Package and Silicon combination for low $r_{\text{DS}(\text{on})}$ and high efficiency
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

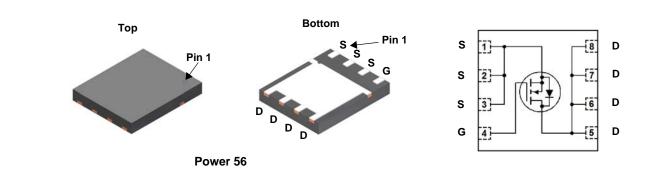


General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency and to minimize switch node ringing of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge and extremely low $r_{DS(on)}$.

Applications

- OringFET
- Synchronous Rectifier



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

| Symbol | Parameter | | | Ratings | Units | |
|-----------------------------------|--|------------------------|-----------|-------------|-------|--|
| V _{DS} | Drain to Source Voltage | | | 30 | V | |
| V _{GS} | Gate to Source Voltage | | (Note 4) | ±20 | V | |
| I _D | Drain Current -Continuous | T _C = 25 °C | | 200 | | |
| | -Continuous | T _A = 25 °C | (Note 1a) | 55 400 | A | |
| | -Pulsed | | (Note 5) | | | |
| E _{AS} | Single Pulse Avalanche Energy | | (Note 3) | 1536 | mJ | |
| P _D | Power Dissipation | T _C = 25 °C | | 156 | W | |
| | Power Dissipation | T _A = 25 °C | (Note 1a) | 2.7 | VV | |
| T _J , T _{STG} | Operating and Storage Junction Temperature F | Range | | -55 to +150 | °C | |

Thermal Characteristics

| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 0.83 | °C/W |
|-----------------|---|------|------|
| R_{\thetaJA} | Thermal Resistance, Junction to Ambient (Note 1a) | 45 | C/W |

Package Marking and Ordering Information

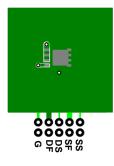
| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|----------|----------|-----------|------------|------------|
| FDMS8050 | FDMS8050 | Power 56 | 13 " | 12 mm | 3000 units |



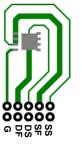
March 2015

| $\begin{array}{c c} \Delta BV_{DSS} \\ \hline \Delta T_J \\ \hline D_{SS} \\ \hline d_{T_J} \\ \hline C \hline \hline C \hline \hline C \\ \hline C \hline \hline \hline C \hline \hline \hline \hline \hline C \hline \hline$ | Drain to Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate to Source Leakage Current teristics Gate to Source Threshold Voltage Gate to Source Threshold Voltage Temperature Coefficient Static Drain to Source On Resistance Forward Transconductance | $\begin{split} & I_D = 750 \ \mu\text{A}, \ V_{GS} = 0 \ V \\ & I_D = 750 \ \mu\text{A}, \ \text{referenced to } 25 \ ^\circ\text{C} \\ & V_{DS} = 24 \ \text{V}, \ V_{GS} = 0 \ \text{V} \\ & V_{GS} = 20 \ \text{V}, \ V_{DS} = 0 \ \text{V} \\ & V_{GS} = 20 \ \text{V}, \ V_{DS} = 0 \ \text{V} \\ & V_{GS} = 10 \ \text{V}, \ I_D = 750 \ \mu\text{A} \\ & I_D = 750 \ \mu\text{A}, \ \text{referenced to } 25 \ ^\circ\text{C} \\ & V_{GS} = 10 \ \text{V}, \ I_D = 55 \ \text{A} \\ & V_{GS} = 10 \ \text{V}, \ I_D = 55 \ \text{A}, \ T_J = 125 \ ^\circ\text{C} \\ & V_{DS} = 5 \ \text{V}, \ I_D = 55 \ \text{A} \\ \end{split}$ | 30 | 20 20 1.8 -6 0.5 0.7 0.7 333 | 1 100 3.0 0.65 0.9 0.9 | V mV/°C μA nA V mV/°C mV/°C |
|--|--|--|-----|---|---------------------------------------|---|
| $\begin{array}{c c c c c c c c c c c c c c c c c c c $ | Drain to Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate to Source Leakage Current teristics Gate to Source Threshold Voltage Gate to Source Threshold Voltage Temperature Coefficient Static Drain to Source On Resistance Forward Transconductance | $\begin{split} & V_{DS} = 750 \ \mu\text{A}, \text{ referenced to } 25 \ ^{\circ}\text{C} \\ & V_{DS} = 24 \ \text{V}, \ \text{V}_{GS} = 0 \ \text{V} \\ & V_{GS} = 20 \ \text{V}, \ \text{V}_{DS} = 0 \ \text{V} \\ & V_{GS} = 20 \ \text{V}, \ \text{V}_{DS} = 0 \ \text{V} \\ & V_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 750 \ \mu\text{A} \\ & I_{D} = 750 \ \mu\text{A}, \text{ referenced to } 25 \ ^{\circ}\text{C} \\ & V_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A} \\ & V_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{S} = 125 \ ^{\circ}\text{C} \\ \end{split}$ | | 1.8 -6 0.5 0.7 0.7 | 100 3.0 0.65 0.9 | mV/°C μA nA V mV/°C |
| $\begin{array}{c c} \Delta B V_{DSS} & F \\ \hline \Delta T_J & C \\ \hline \Delta T_J & C \\ \hline \Delta T_J & C \\ \hline I_{DSS} & 2 \\ \hline I_{DSS} & 2 \\ \hline I_{DSS} & C \\ \hline \begin{array}{c} \Delta V_{GS}(th) & C \\ \hline \Delta V_{GS}(th) & C \\ \hline \Delta T_J & T \\ \hline \end{array} \\ \hline \end{array} \\ \begin{array}{c} r_{DS}(on) & S \\ \hline \end{array} \\ \hline \begin{array}{c} S \\ \hline \end{array} \\ \hline \end{array} \\ \hline \begin{array}{c} P_{S} & F \\ \hline \end{array} \\ \hline \end{array} \\ \hline \begin{array}{c} Dynamic C \\ \hline \\ C_{iss} & I \\ \hline \\ C_{oss} & C \\ \hline \end{array} \\ \hline \end{array} $ | Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate to Source Leakage Current teristics Gate to Source Threshold Voltage Gate to Source Threshold Voltage Temperature Coefficient Static Drain to Source On Resistance Forward Transconductance Characteristics | $\begin{split} & V_{DS} = 750 \ \mu\text{A}, \text{ referenced to } 25 \ ^{\circ}\text{C} \\ & V_{DS} = 24 \ \text{V}, \ \text{V}_{GS} = 0 \ \text{V} \\ & V_{GS} = 20 \ \text{V}, \ \text{V}_{DS} = 0 \ \text{V} \\ & V_{GS} = 20 \ \text{V}, \ \text{V}_{DS} = 0 \ \text{V} \\ & V_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 750 \ \mu\text{A} \\ & I_{D} = 750 \ \mu\text{A}, \text{ referenced to } 25 \ ^{\circ}\text{C} \\ & V_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A} \\ & V_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{GS} = 10 \ \text{V}, \ \text{I}_{D} = 55 \ \text{A}, \ \text{V}_{S} = 125 \ ^{\circ}\text{C} \\ \end{split}$ | | 1.8 -6 0.5 0.7 0.7 | 100 3.0 0.65 0.9 | mV/°C μA nA V mV/°C |
| $\begin{array}{c c} \hline GSS & G \\ \hline GSS & G \\ \hline On Charact \\ \hline V_{GS(th)} & G \\ \hline \Delta V_{GS(th)} & G \\ \hline \Delta T_J & G \\ \hline \Gamma_{DS(on)} & G \\ \hline g_{FS} & F \\ \hline Dynamic Cl \\ \hline C_{iss} & G \\ \hline C_{rss} & F \\ \hline \end{array}$ | Gate to Source Leakage Current teristics Gate to Source Threshold Voltage Gate to Source Threshold Voltage Temperature Coefficient Static Drain to Source On Resistance Forward Transconductance Characteristics | $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ $V_{GS} = V_{DS}, I_D = 750 \mu\text{A}$ $I_D = 750 \mu\text{A}, \text{ referenced to } 25 ^\circ\text{C}$ $V_{GS} = 10 V, I_D = 55 A$ $V_{GS} = 4.5 V, I_D = 47 A$ $V_{GS} = 10 V, I_D = 55 A, T_J = 125 ^\circ\text{C}$ | 1.0 | -6 0.5 0.7 0.7 | 100 3.0 0.65 0.9 | NA V mV/°C |
| $\begin{array}{c c} I_{GSS} & I \\ \hline \\ Dn Charact \\ \hline \\ V_{GS(th)} & I \\ \hline \\ \hline \\ \Delta V_{GS(th)} \\ \hline \\ \hline \\ \Delta T_J & I \\ \hline \\ \\ r_{DS(on)} & I \\ \hline \\ \hline \\ g_{FS} & F \\ \hline \\ \hline \\ \hline \\ Dynamic Cl \\ \hline \\ \hline \\ C_{iss} & I \\ \hline \\ \hline \\ C_{oss} & G \\ \hline \\$ | teristics Gate to Source Threshold Voltage Gate to Source Threshold Voltage Temperature Coefficient Static Drain to Source On Resistance Forward Transconductance | $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ $V_{GS} = V_{DS}, I_D = 750 \mu\text{A}$ $I_D = 750 \mu\text{A}, \text{ referenced to } 25 ^\circ\text{C}$ $V_{GS} = 10 V, I_D = 55 A$ $V_{GS} = 4.5 V, I_D = 47 A$ $V_{GS} = 10 V, I_D = 55 A, T_J = 125 ^\circ\text{C}$ | 1.0 | -6 0.5 0.7 0.7 | 3.0 0.65 0.9 | V mV/°C |
| $\begin{array}{c c} V_{GS(th)} & C \\ \hline \Delta V_{GS(th)} & T \\ \hline \Delta T_J & T \\ \hline r_{DS(on)} & S \\ \hline g_{FS} & F \\ \hline Dynamic Cl \\ \hline C_{iss} & I \\ \hline C_{oss} & C \\ \hline C_{rss} & F \end{array}$ | Gate to Source Threshold Voltage Gate to Source Threshold Voltage Temperature Coefficient Static Drain to Source On Resistance Forward Transconductance | $I_{D} = 750 \ \mu\text{A}, \text{ referenced to } 25 \ ^{\circ}\text{C}$ $V_{GS} = 10 \ \text{V}, I_{D} = 55 \ \text{A}$ $V_{GS} = 4.5 \ \text{V}, I_{D} = 47 \ \text{A}$ $V_{GS} = 10 \ \text{V}, I_{D} = 55 \ \text{A}, T_{J} = 125 \ ^{\circ}\text{C}$ | 1.0 | -6 0.5 0.7 0.7 | 0.65 | mV/°C |
| $\begin{array}{c c} V_{GS(th)} & C \\ \hline \Delta V_{GS(th)} & T \\ \hline \Delta T_J & T \\ \hline r_{DS(on)} & S \\ \hline g_{FS} & F \\ \hline Dynamic Cl \\ \hline C_{iss} & I \\ \hline C_{oss} & C \\ \hline C_{rss} & F \end{array}$ | Gate to Source Threshold Voltage Gate to Source Threshold Voltage Temperature Coefficient Static Drain to Source On Resistance Forward Transconductance | $I_{D} = 750 \ \mu\text{A}, \text{ referenced to } 25 \ ^{\circ}\text{C}$ $V_{GS} = 10 \ \text{V}, I_{D} = 55 \ \text{A}$ $V_{GS} = 4.5 \ \text{V}, I_{D} = 47 \ \text{A}$ $V_{GS} = 10 \ \text{V}, I_{D} = 55 \ \text{A}, T_{J} = 125 \ ^{\circ}\text{C}$ | 1.0 | -6 0.5 0.7 0.7 | 0.65 | mV/°C |
| $\begin{array}{c c} \frac{\Delta V_{GS(th)}}{\Delta T_J} & f \\ \hline \\ r_{DS(on)} & g \\ \hline \\ g_{FS} & f \\ \hline \\$ | Gate to Source Threshold Voltage Temperature Coefficient Static Drain to Source On Resistance Forward Transconductance Characteristics | $I_{D} = 750 \ \mu\text{A}, \text{ referenced to } 25 \ ^{\circ}\text{C}$ $V_{GS} = 10 \ \text{V}, I_{D} = 55 \ \text{A}$ $V_{GS} = 4.5 \ \text{V}, I_{D} = 47 \ \text{A}$ $V_{GS} = 10 \ \text{V}, I_{D} = 55 \ \text{A}, T_{J} = 125 \ ^{\circ}\text{C}$ | | 0.5 0.7 0.7 | 0.9 | |
| g _{FS} F Dynamic Cl C _{iss} I C _{oss} C C _{rss} F | Forward Transconductance | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 47 \text{ A}$ $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 55 \text{ A}, \text{ T}_{J} = 125 \text{ °C}$ | | 0.7 0.7 | 0.9 | mΩ |
| g _{FS} F Dynamic Cl C _{iss} I C _{oss} C C _{rss} F | Forward Transconductance | V_{GS} = 10 V, I_D = 55 A, T_J = 125 °C | | 0.7 | | mΩ |
| 9 _{FS} F Dynamic Cl C _{iss} I C _{oss} (C _{rss} F | haracteristics | | | - | 0.9 | 1 |
| Dynamic Cl C_{iss} I C_{oss} C C_{rss} F | haracteristics | V _{DS} = 5 V, I _D = 55 A | | 333 | | 1 |
| Dynamic Cl C _{iss} I C _{oss} C C _{rss} F | | | | | 1 | S |
| 155 | Input Capacitance Output Capacitance Reverse Transfer Capacitance | − V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz | | 16150 4455 220 | 22610 6240 310 | pF pF |
| | Reverse Transfer Capacitance | | | 220 | 310 | pF |
| R _g (| Gate Resistance | | | 1.0 | 3.0 | Ω |
| Switching (| Characteristics | | | | | |
| t _{d(on)} | Turn-On Delay Time | | | 29 | 47 | ns |
| t _r F | Rise Time | V _{DD} = 15 V, I _D = 55 A, | | 22 | 36 | ns |
| t _{d(off)} | Turn-Off Delay Time | V_{GS} = 10 V, R_{GEN} = 6 Ω | | 87 | 139 | ns |
| | Fall Time | | | 16 | 28 | ns |
| Q _g 1 | Total Gate Charge | V _{GS} = 0 V to 10 V | | 204 | 285 | nC |
| Q _g 1 | Total Gate Charge | $V_{GS} = 0 V \text{ to } 4.5 V V_{DD} = 15 V,$ | | 93 | 130 | nC |
| | Gate to Source Charge | I _D = 55 A | | 41 | | nC |
| | Gate to Drain "Miller" Charge | | | 18 | | nC |
| Drain-Sour | ce Diode Characteristics | | | | | |
| | Source to Drain Diode Forward Voltage | $V_{GS} = 0 V, I_S = 2.2 A$ (Note 2) | | 0.64 | 1.2 1.2 | V |
| | | $V_{GS} = 0 V, I_S = 55 A$ (Note 2) | | 0.74 | | - |
| | Reverse Recovery Time Reverse Recovery Charge | — I _F = 55 A, di/dt = 100 A/μs | | 77 141 | 124 226 | ns nC |

R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



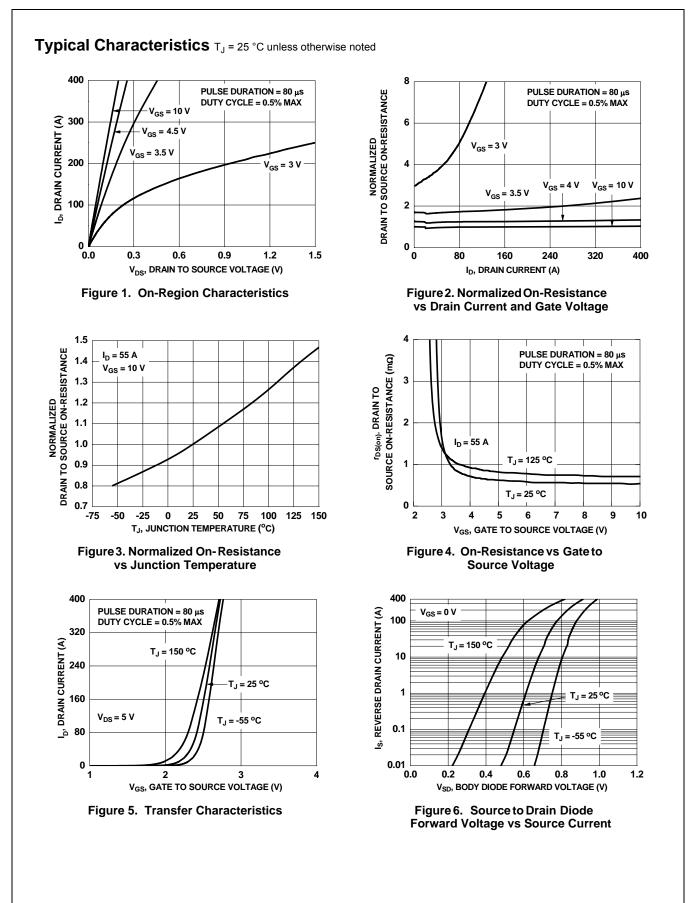
a. 45 °C/W when mounted on a 1 in² pad of 2 oz copper.

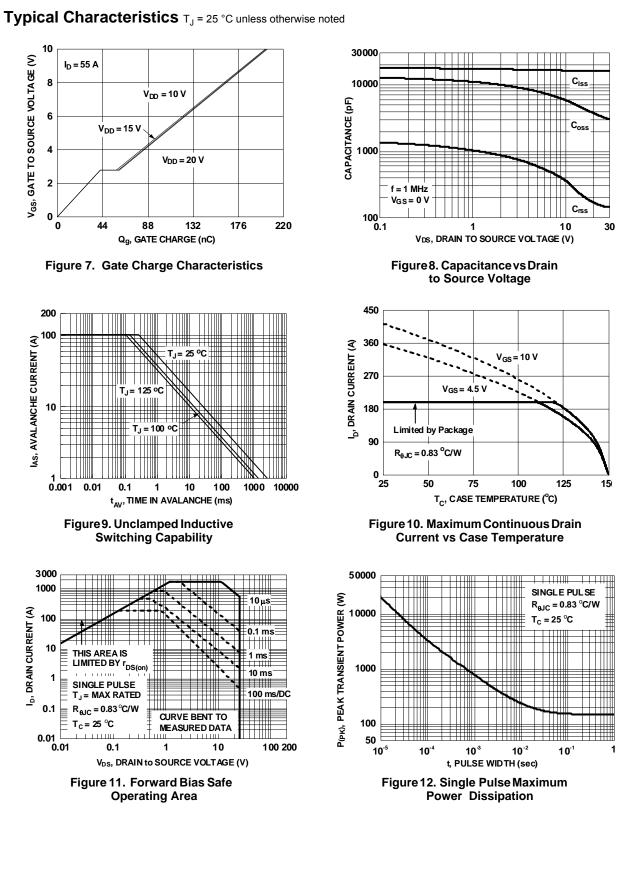


b. 115 °C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%. 3. E_{AS} of 1536 mJ is based on starting T_J = 25 °C, L = 3 mH, I_{AS} = 32 A, V_{DD} = 30 V, V_{GS} = 10 V, 100% test at L = 0.3 mH, I_{AS} = 69 A. 4. As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied. 5. Pulse Id limited by junction temperature, td ≤ 100 μ s. Please refer to SOA curve for more details.

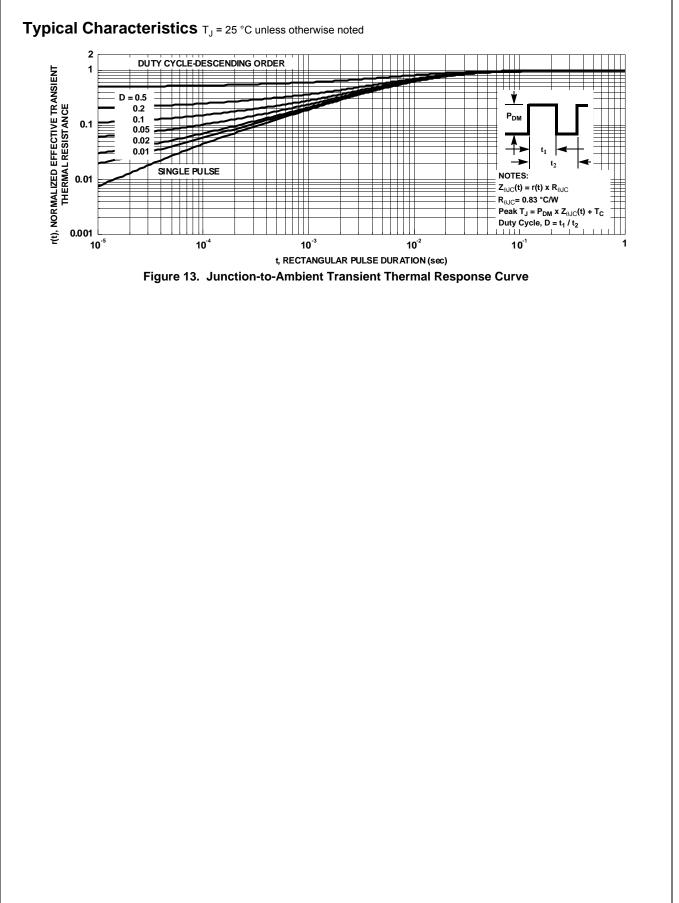
FDMS8050 N-Channel PowerTrench[®] MOSFET



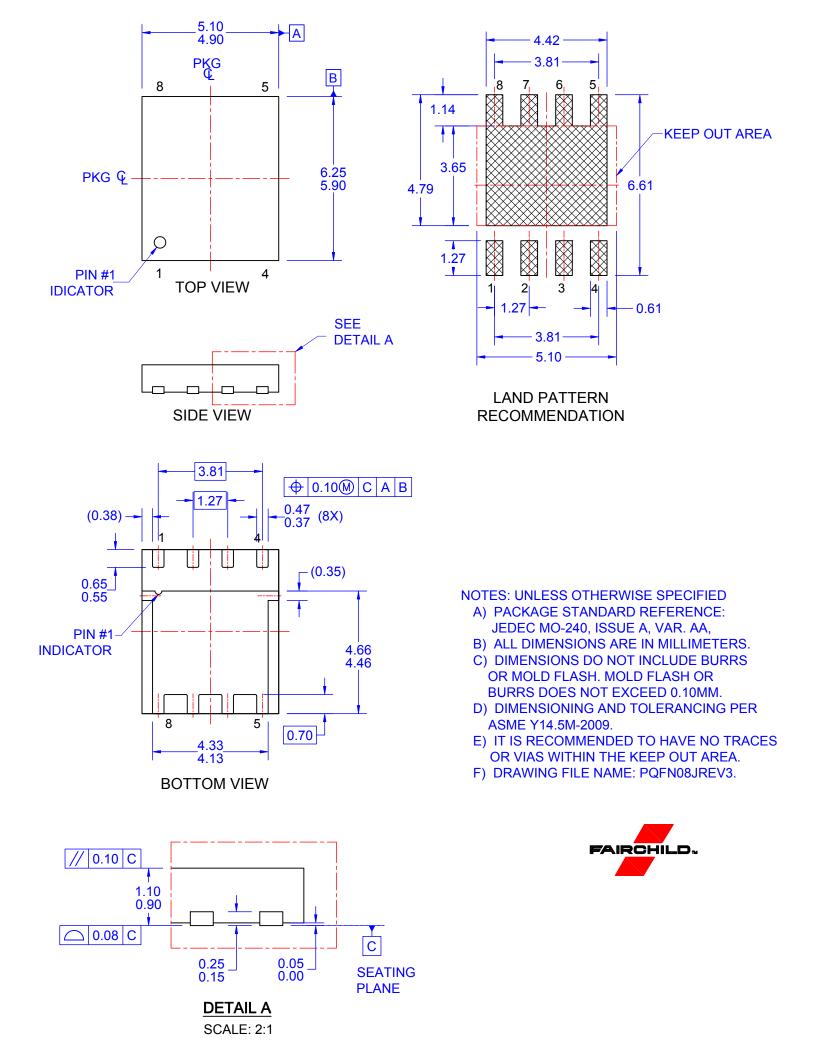


FDMS8050 Rev. 1.2

FDMS8050 N-Channel PowerTrench[®] MOSFET



FDMS8050 N-Channel PowerTrench[®] MOSFET



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